

Abstract of the Disclosure

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A method and apparatus is provided for more efficiently application of photoresist to a wafer surface. One aspect of the method comprises applying solvent to the wafer and spinning it to coat the entire wafer surface prior to the application of photoresist. This reduces surface tension on the wafer and reduces the amount of resist required to achieve a high quality film. The apparatus comprises adding a third solenoid and nozzle to the coating unit to accommodate the application of solvent to the center of the wafer surface. The method also describes incorporating a new solvent comprising Di-Acetone Alcohol, which is a low-pressure solvent, providing extended process latitudes and reduced material expenditures.

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